ICS 31.180 SLOVENSKÁ TECHNICKÁ NORMA December 2023

STN	**Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy Časť 2-803: Skúšobné metódy na rozpínanie základných druhov materiálov a dosiek s plošnými spojmi v osi Z**	**STN EN IEC 61189-2-803** 34 6513

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-803: Test methods for Z-axis expansion of base materials and printed boards

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/23

Obsahuje: EN IEC 61189-2-803:2023, IEC 61189-2-803:2023

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EUROPEAN STANDARD

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EUROPÄISCHE NORM

EN IEC 61189-2-803

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English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-803: Test methods for Z-axis expansion of base materials and printed boards (IEC 61189-2-803:2023)

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-803: Méthodes d'essai pour la dilatation suivant l'axe Z des matériaux de base et des cartes imprimées (IEC 61189-2-803:2023)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-803: Prüfverfahren für die Z-Achsen-Ausdehnung von Basismaterialien und Leiterplatten (IEC 61189-2-803:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

Ref. No. EN IEC 61189-2-803:2023 E

European foreword

The text of document 91/1760/CDV, future edition 1 of IEC 61189-2-803, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-803:2023.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2024-05-30
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2026-08-30

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The text of the International Standard IEC 61189-2-803:2023 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-

IEC 61189-2-803

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INTERNATIONAL STANDARD

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-803: Test methods for Z-axis expansion of base materials and printed boards

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 61189-2-803 has been prepared by IEC technical committee TC 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1760/CDV	91/1863/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-803: Test methods for Z-axis expansion of base materials and printed boards

1 Scope

This part of IEC 61189 specifies a test method to determine the Z-axis expansion of base materials and printed boards using a thermomechanical analyser (TMA).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194-1, *Printed boards design, manufacture and assembly – Vocabulary – Part 1: Common usage in printed board and electronic assembly technologies*